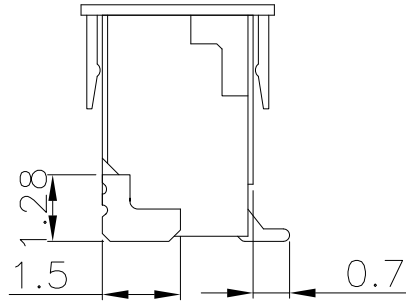
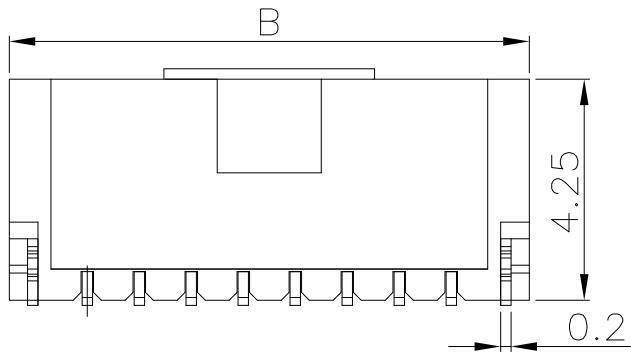


P.C.B LAYOUT MOUNTING PATTERN

PIN NO.	DIMENSION	
	A	B
02	1.00	4.00
03	2.00	5.00
04	3.00	6.00
05	4.00	7.00
06	5.00	8.00
07	6.00	9.00
08	7.00	10.00
09	8.00	11.00
10	9.00	12.00
11	10.00	13.00
12	11.00	14.00
13	12.00	15.00
14	13.00	16.00
15	14.00	17.00
16	15.00	18.00
17	16.00	19.00
18	17.00	20.00
19	18.00	21.00
20	19.00	22.00



- 1.MATERIAL
- HOUSING:HTN
- CONTACT:PHOSPHOR BRONZE
- SOLDER PAD:BRASS
- 2.PLATING: TIN OVER NICKEL
- 3.SPECIFICATION
- CURRENT RATING:1A AC,DC
- VOLTAGE RATING:250V AC,DC
- TEMPERATURE RANGE:-25C~+85C
- CONTACT RESISTANCE:20M MAX.
- INSULATION RESISTANCE:1000M MIN.
- WITHSTANDING VOLTAGE:500V AC/MINUTE

ITEM NO.	DESCRIPTION	DRAWN	DATE
4	更新材質	Jack	121422
3	更新PCB LAYOUT	Jack	091420
2	更新PCB LAYOUT	Jack	032118
1	更新B尺寸標示位置	Jack	101515

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	12/14/22		MODLE	WAFER 1.0 SMT 180度(JST)
CHECKED BY:	DATE	FINISH	SCALE	SIZE
Jacky Chen	12/14/22		1 : 1	A4
APPROVED BY:	DATE	SHEET NO.	DWG NO.	VER
Tony Kao	12/14/22	1 of 1	WF-1000VSxx-S304	R4
		PART NO.	WF-1000VSxx-S304	